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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	CANbus, I ² C, SCI, SPI, UART/USART, USB
Peripherals	LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 11x14b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	36-WFLGA
Supplier Device Package	36-WFLGA (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r7fs124762a01clm-ac0

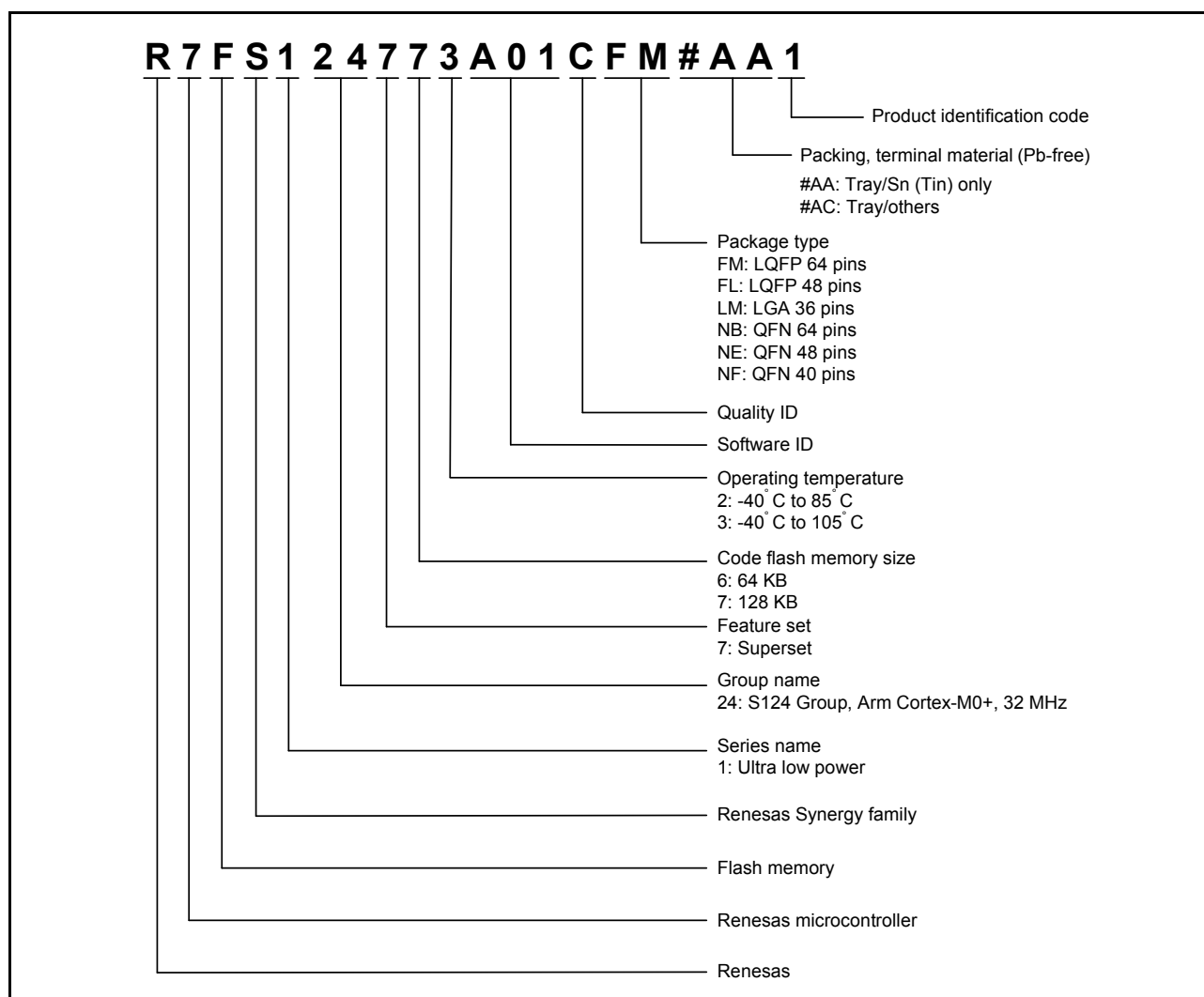


Figure 1.2 Part numbering scheme

Table 1.12 Product list

Product part number	Orderable part number	Package code	Code flash	Data flash	SRAM	Operating temperature
R7FS124773A01CFM	R7FS124773A01CFM#AA1	PLQP0064KB-C	128 KB	4 KB	16 KB	-40 to +105°C
R7FS124773A01CNB	R7FS124773A01CNB#AC1	PWQN0064LA-A				-40 to +105°C
R7FS124773A01CFL	R7FS124773A01CFL#AA1	PLQP0048KB-B				-40 to +105°C
R7FS124773A01CNE	R7FS124773A01CNE#AC1	PWQN0048KB-A				-40 to +105°C
R7FS124773A01CNF	R7FS124773A01CNF#AC1	PWQN0040KC-A				-40 to +105°C
R7FS124772A01CLM	R7FS124772A01CLM#AC1	PWLG0036KA-A				-40 to +85°C
R7FS124763A01CFM	R7FS124763A01CFM#AA1	PLQP0064KB-C	64 KB			-40 to +105°C
R7FS124763A01CFL	R7FS124763A01CFL#AA1	PLQP0048KB-B				-40 to +105°C
R7FS124762A01CLM	R7FS124762A01CLM#AC1	PWLG0036KA-A				-40 to +85°C

Note: Earlier products with orderable part number suffix AA0 and AC0 have a restriction in AES functions. If AES functions are required for your application, refer to the products with orderable part number suffix AA1 or AC1. For details on the differences of AES functions between AA0/AC0 and AA1/AC1 products, see *Technical Update (TN-SY*-A024A/E)*. Contact your Renesas sales representative for additional information.

Table 1.14 Pin functions (3 of 3)

Function	Signal	I/O	Description
ACMPLP	VCOUT	Output	Comparator output pin.
	CMPREF0, CMPREF1	Input	Reference voltage input pins.
	CMPIN0, CMPIN1	Input	Analog voltage input pins.
CTSU	TS00 to TS28, TS30, TS31	Input	Capacitive touch detection pins (touch pins).
	TSCAP	-	Secondary power supply pin for the touch driver.
KINT	KR00 to KR07	Input	Key interrupt input pins.
I/O ports	P000 to P004, P010 to P015	I/O	General-purpose input/output pins.
	P100 to P113	I/O	General-purpose input/output pins.
	P200	Input	General-purpose input pin.
	P201, P204 to P206, P212, P213	I/O	General-purpose input/output pins.
	P214, P215	Input	General-purpose input pins.
	P300 to P304	I/O	General-purpose input/output pins.
	P400 to P403, P407 to P411	I/O	General-purpose input/output pins.
	P500 to P502	I/O	General-purpose input/output pins.

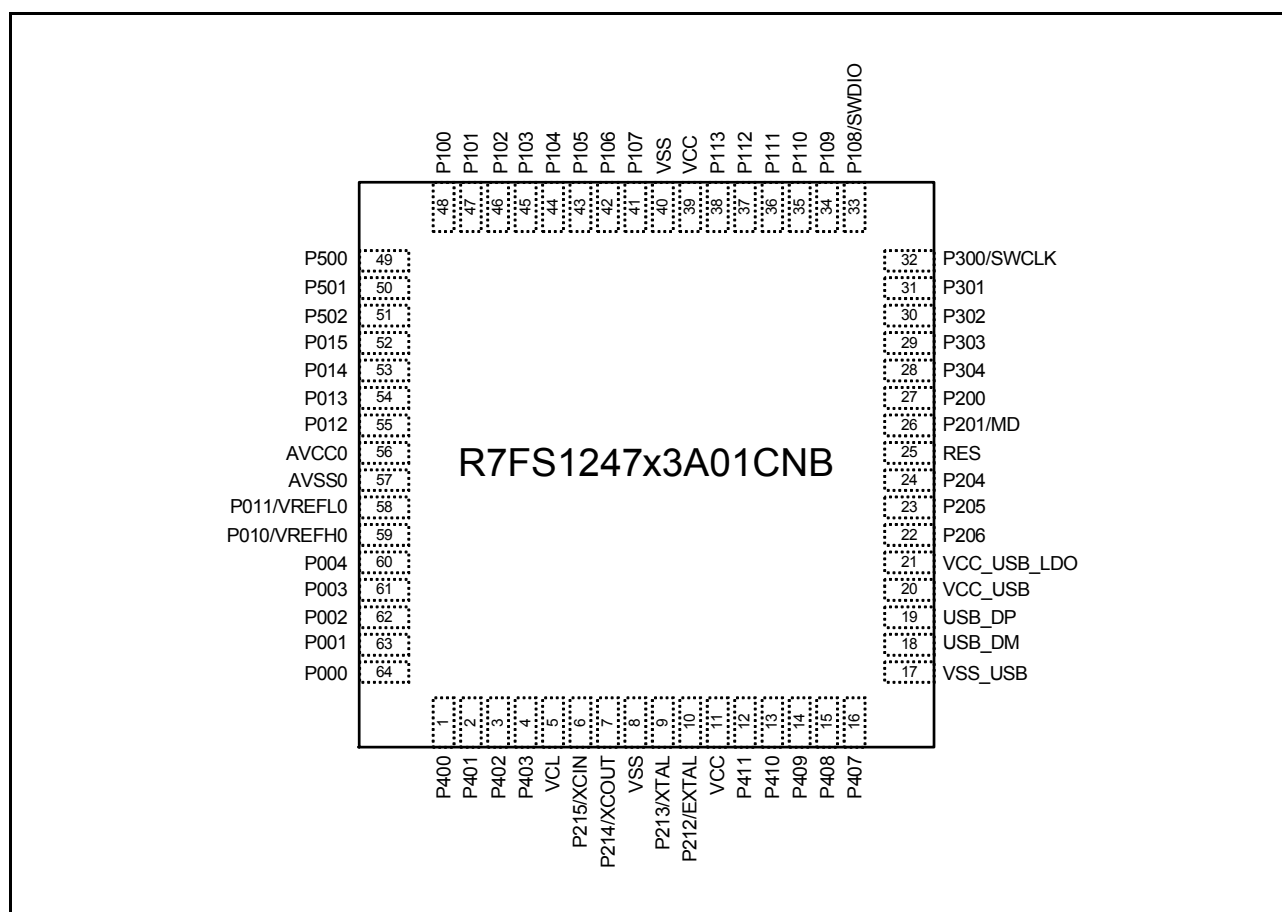


Figure 1.4 Pin assignment for QFN 64-pin (top view)

Pin number					Power, System, Clock, Debug, CAC	I/O ports	Timers				Communication Interfaces				Analog		HMI	
LQFP64, QFN64	LQFP48	QFN48	QFN40	LGA36			AGT	GT_OPS, POEG	GPT	RTC	USBFS, CAN	SCI	IIC	SPI	ADC14	DAC12, ACMP	CTSU	Interrupt
35	27	27	23	D5		P110		GT_OVLO_A	GTIOC1B_A		CRX0_A	CTS0_RT S0_C/ SS0_C/ RXD9_B/ MISO9_B/ SCL9_B		MISOB_B		VCOU	TS11	IRQ3
36	28	28	24	D6		P111			GTIOC3A_A			SCK0_C/ SCK9_B		RSPCKB_B			TS12	IRQ4
37	29	29	25	C6		P112			GTIOC3B_A			TXD0_C/ MOSI0_C/ SDA0_C					TSCAP_C	
38	-	-	-	-		P113												
39	30	30	-	-	VCC													
40	31	31	-	-	VSS													
41	-	-	-	-		P107			GTIOC0A_B									KR07
42	-	-	-	-		P106			GTIOC0B_B					SSLA3_A				KR06
43	-	-	-	-		P105		GTETRG_A_C						SSLA2_A				KR05/ IRQ0
44	32	32	26	-		P104		GTETRG_B_B				RXD0_C/ MISO0_C/ SCL0_C		SSLA1_A			TS13	KR04/ IRQ1
45	33	33	27	C3		P103		GTOWUP_A	GTIOC2A_A		CTX0_C	CTS0_RT S0_A/ SS0_A		SSLA0_A	AN019	CMPREF1	TS14	KR03
46	34	34	28	C4		P102	AGT00	GTOWLO_A	GTIOC2B_A		CRX0_C	SCK0_A		RSPCKA_A	AN020/ ADTRG0_A	CMPIN1	TS15	KR02
47	35	35	29	C5		P101	AGTEE0	GTETRG_B_A	GTIOC5A_A			TXD0_A/ MOSI0_A/ SDA0_A/ CTS1_RT S1_A/ SS1_A	SDA1_B	MOSIA_A	AN021	CMPREF0	TS16	KR01/ IRQ1
48	36	36	30	B6		P100	AGTIO0_A	GTETRG_A_A	GTIOC5B_A			RXD0_A/ MISO0_A/ SCL0_A/ SCK1_A	SCL1_B	MISOA_A	AN022	CMPIN0	TS26	KR00/ IRQ2
49	37	37	-	-		P500	AGTOA0	GTIU_B	GTIOC2A_B						AN016		TS27	
50	-	-	-	-		P501	AGTOB0	GTIV_B	GTIOC2B_B						AN017			
51	-	-	-	-		P502		GTIW_B	GTIOC3B_B						AN018			
52	38	38	31	A6		P015									AN010		TS28	IRQ7
53	39	39	32	A5		P014									AN009	DA0		
54	40	40	33	B5		P013									AN008			
55	41	41	34	B4		P012									AN007			
56	42	42	35	A4	AVCC0													
57	43	43	36	A3	AVSS0													
58	44	44	37	B3	VREFL0	P011									AN006		TS31	
59	45	45	38	A2	VREFH0	P010									AN005		TS30	
60	-	-	-	-		P004									AN004		TS25	IRQ3
61	-	-	-	-		P003									AN003		TS24	
62	46	46	-	-		P002									AN002		TS23	IRQ2
63	47	47	39	-		P001									AN001		TS22	IRQ7
64	48	48	40	B2		P000									AN000		TS21	IRQ6

Note: Several pin names have the added suffix of _A, _B, _C, and _D. The suffix can be ignored when assigning functionality.

2.2.7 P408, P409 I/O Pin Output Characteristics of Middle Drive Capacity

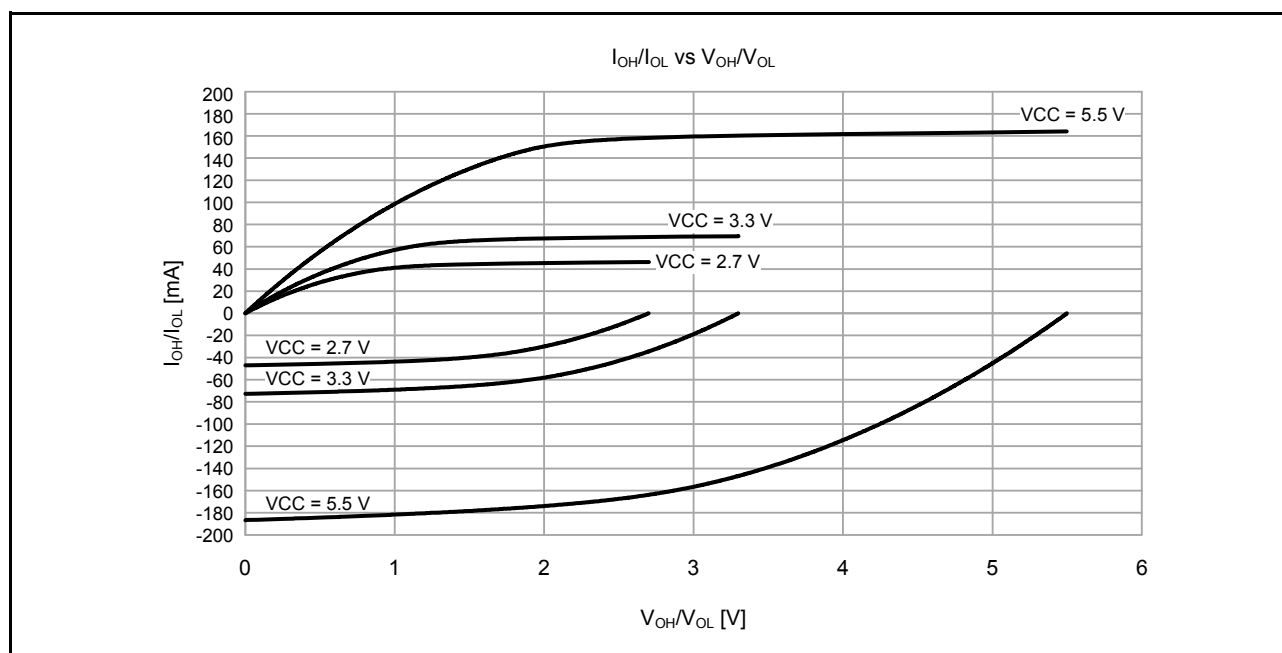


Figure 2.12 V_{OH}/V_{OL} and I_{OH}/I_{OL} voltage characteristics at $T_a = 25^\circ\text{C}$ when middle drive output is selected (reference data)

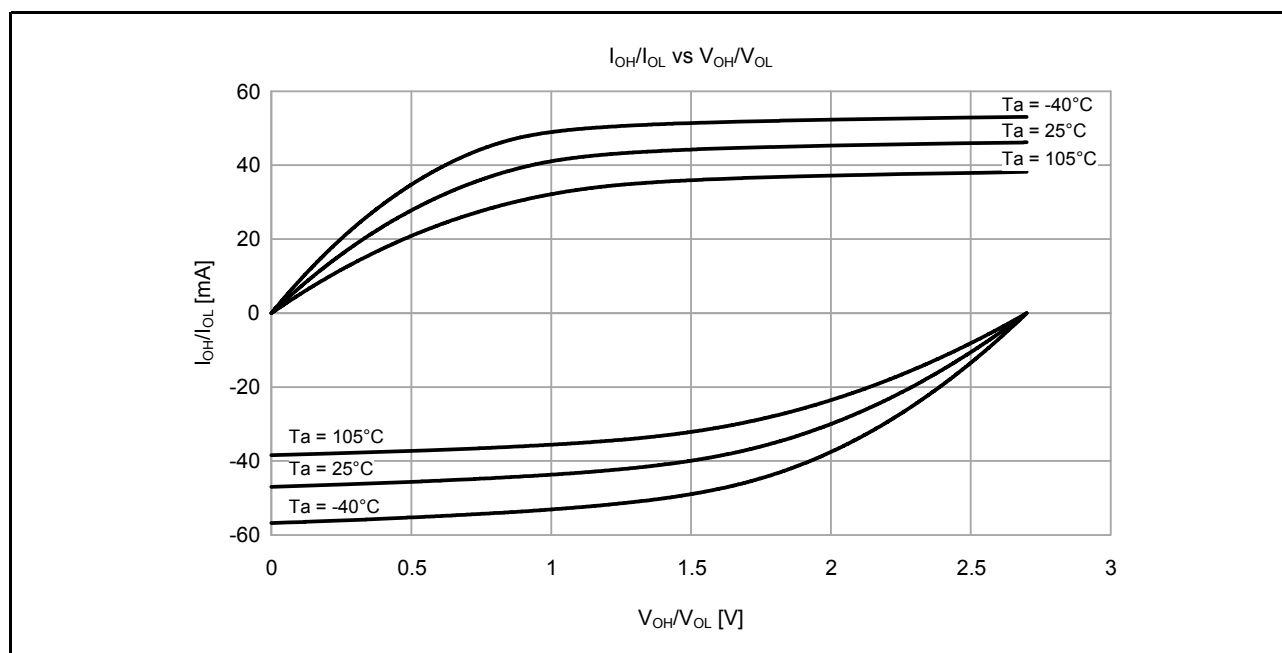


Figure 2.13 V_{OH}/V_{OL} and I_{OH}/I_{OL} temperature characteristics at $V_{CC} = 2.7\text{ V}$ when middle drive output is selected (reference data)

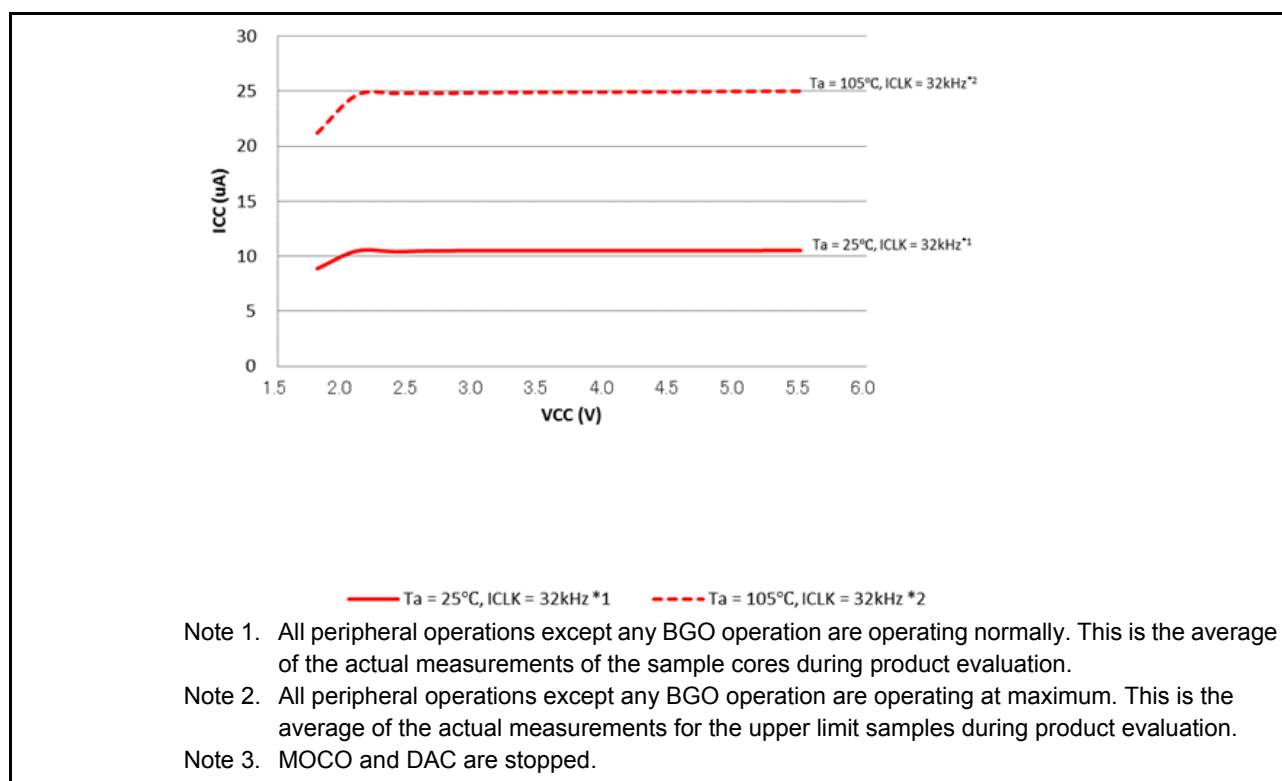


Figure 2.21 Voltage dependency in subosc-speed operating mode (reference data)

Table 2.12 Operating and standby current (2)

Conditions: $V_{CC} = AV_{CC0} = 1.6$ to 5.5 V

Parameter			Symbol	Typ* ³	Max	Unit	Test conditions
Supply current* ¹	Software Standby mode* ²	T _a = 25°C	I _{CC}	0.4	1.5	µA	-
		T _a = 55°C		0.6	5.5		
		T _a = 85°C		1.2	10.0		
		T _a = 105°C		2.6	40.0		
	Increment for RTC operation with low-speed on-chip oscillator* ⁴			0.4	-	-	
	Increment for RTC operation with sub-clock oscillator* ⁴			0.5	-	SOMCR.SODRV[1:0] are 11b (Low power mode 3)	
				1.3	-	SOMCR.SODRV[1:0] are 00b (normal mode)	

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOS transistors are in the off state.

Note 2. The IWDG and LVD are not operating.

Note 3. $V_{CC} = 3.3$ V.

Note 4. Includes the current of low-speed on-chip oscillator or sub-oscillation circuit.

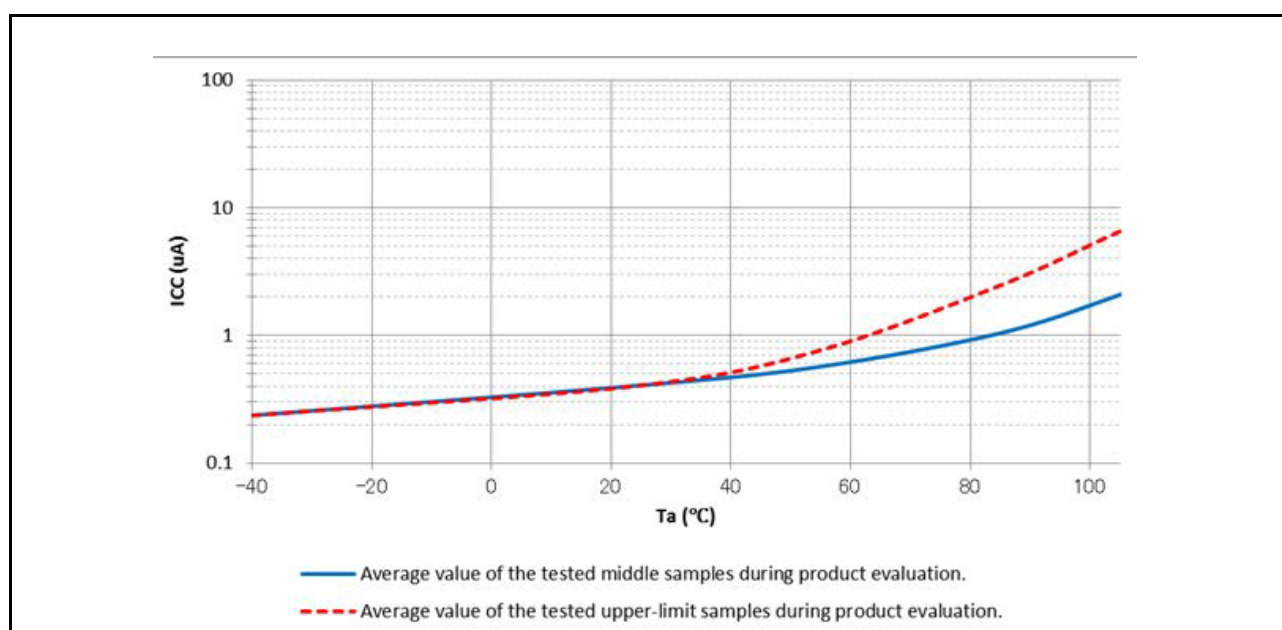


Figure 2.22 Temperature dependency in Software Standby mode (reference data)

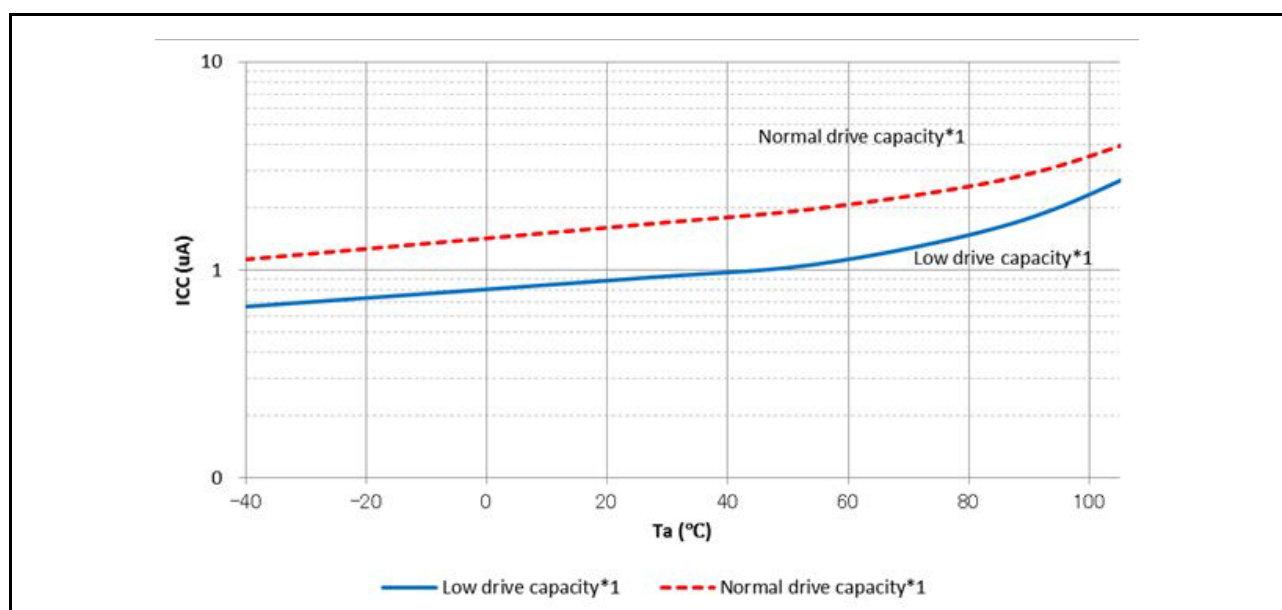


Figure 2.23 Temperature dependency of RTC operation (reference data)

Table 2.13 Operating and standby current (3) (1 of 2)

Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter		Symbol	Min	Typ	Max	Unit	Test conditions
Analog power supply current	During A/D conversion (at high-speed conversion)	I_{AVCC}	-	-	3.0	mA	-
	During A/D conversion (at low-power conversion)		-	-	1.0	mA	-
	During D/A conversion*1		-	0.4	0.8	mA	-
	Waiting for A/D and D/A conversion (all units)*5		-	-	1.0	μA	-
Reference power supply current	During A/D conversion	I_{REFH0}	-	-	150	μA	-
	Waiting for A/D conversion (all units)		-	-	60	nA	-
Temperature sensor		I_{TNS}	-	75	-	μA	-

2.2.10 VCC Rise and Fall Gradient and Ripple Frequency

Table 2.14 Rise and fall gradient characteristics

Conditions: VCC = AVCC0 = 0 to 5.5 V

Parameter		Symbol	Min	Typ	Max	Unit	Test conditions
Power-on VCC rising gradient	Voltage monitor 0 reset disabled at startup	SrVCC	0.02	-	2	ms/V	-
	Voltage monitor 0 reset enabled at startup*1, *2		0.02	-	-		
	SCI Boot mode*2		0.02	-	2		

Note 1. When OFS1.LVDAS = 0.

Note 2. At boot mode, the reset from voltage monitor 0 is disabled regardless of the value of OFS1.LVDAS bit.

Table 2.15 Rising and falling gradient and ripple frequency characteristics

Conditions: VCC = AVCC0 = 1.6 to 5.5 V

The ripple voltage must meet the allowable ripple frequency $f_{r(VCC)}$ within the range between the VCC upper limit (5.5 V) and lower limit (1.6 V).

When the VCC change exceeds VCC $\pm 10\%$, the allowable voltage change rising and falling gradient $dt/dVCC$ must be met.

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Allowable ripple frequency	$f_{r(VCC)}$	-	-	10	kHz	Figure 2.24 $V_{r(VCC)} \leq VCC \times 0.2$
		-	-	1	MHz	Figure 2.24 $V_{r(VCC)} \leq VCC \times 0.08$
		-	-	10	MHz	Figure 2.24 $V_{r(VCC)} \leq VCC \times 0.06$
Allowable voltage change rising and falling gradient	$dt/dVCC$	1.0	-	-	ms/V	When VCC change exceeds VCC $\pm 10\%$

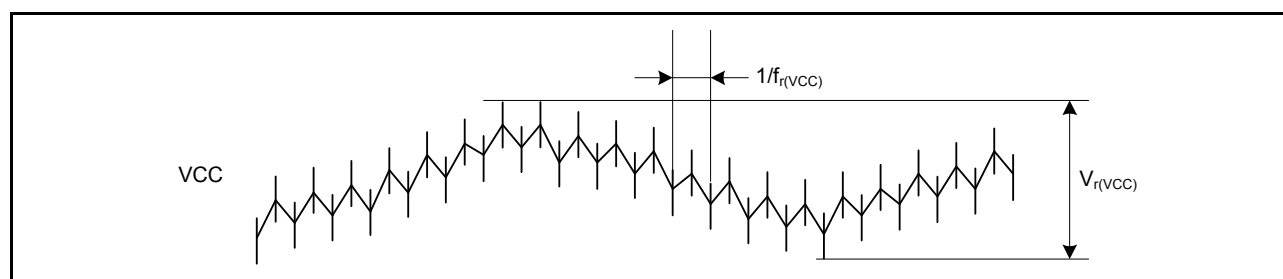


Figure 2.24 Ripple waveform

2.3.5 NMI and IRQ Noise Filter

Table 2.29 NMI and IRQ noise filter

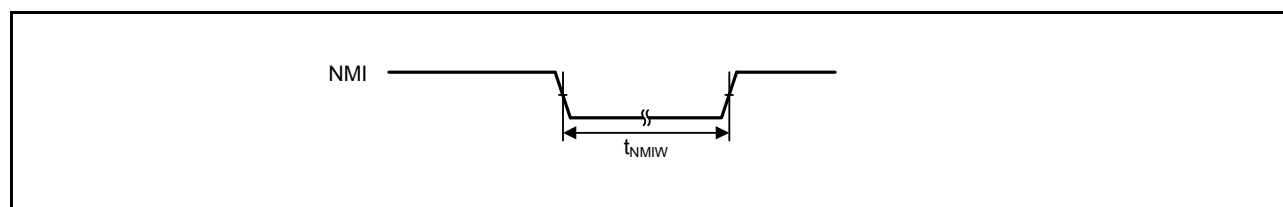
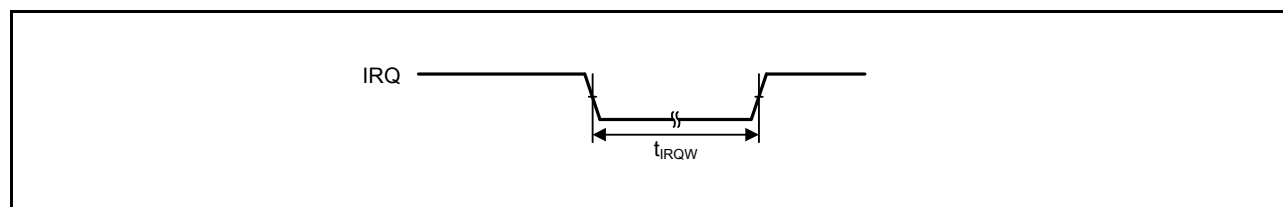
Parameter	Symbol	Min	Typ	Max	Unit	Test conditions	
NMI pulse width	t_{NMIW}	200	-	-	ns	NMI digital filter disabled	$t_{\text{Pcyc}} \times 2 \leq 200 \text{ ns}$
		$t_{\text{Pcyc}} \times 2^{*1}$	-	-			$t_{\text{Pcyc}} \times 2 > 200 \text{ ns}$
		200	-	-		NMI digital filter enabled	$t_{\text{NMICK}} \times 3 \leq 200 \text{ ns}$
		$t_{\text{NMICK}} \times 3.5^{*2}$	-	-			$t_{\text{NMICK}} \times 3 > 200 \text{ ns}$
IRQ pulse width	t_{IRQW}	200	-	-	ns	IRQ digital filter disabled	$t_{\text{Pcyc}} \times 2 \leq 200 \text{ ns}$
		$t_{\text{Pcyc}} \times 2^{*1}$	-	-			$t_{\text{Pcyc}} \times 2 > 200 \text{ ns}$
		200	-	-		IRQ digital filter enabled	$t_{\text{IRQCK}} \times 3 \leq 200 \text{ ns}$
		$t_{\text{IRQCK}} \times 3.5^{*3}$	-	-			$t_{\text{IRQCK}} \times 3 > 200 \text{ ns}$

Note: 200 ns minimum in Software Standby mode.

Note 1. t_{Pcyc} indicates the PCLKB cycle.

Note 2. t_{NMICK} indicates the cycle of the NMI digital filter sampling clock.

Note 3. t_{IRQCK} indicates the cycle of the IRQi digital filter sampling clock (i = 0 to 7).

**Figure 2.33 NMI interrupt input timing****Figure 2.34 IRQ interrupt input timing**

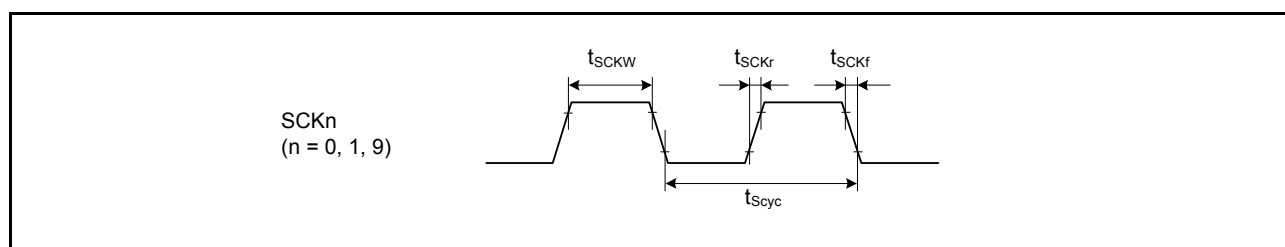


Figure 2.41 SCK clock input timing

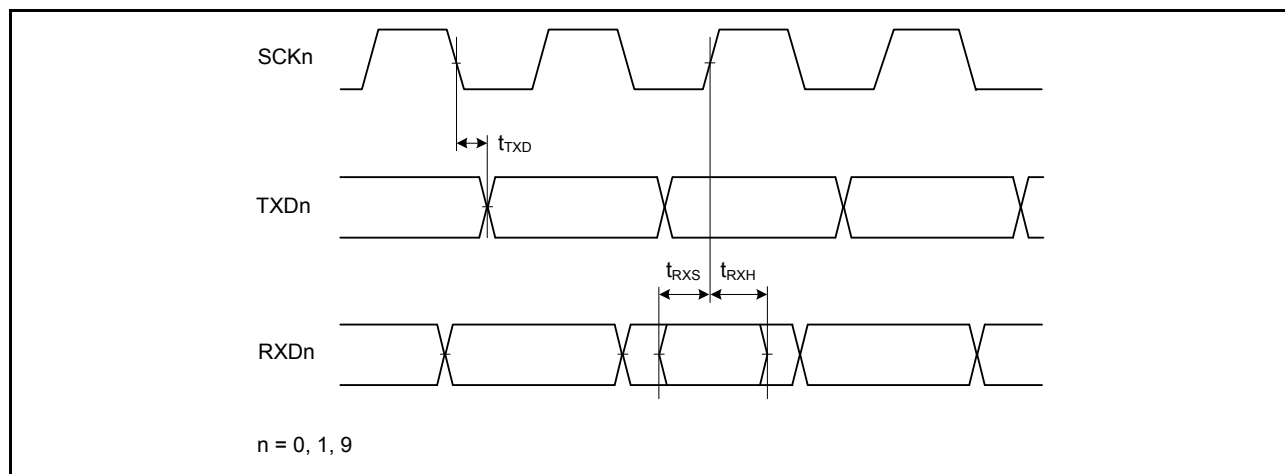


Figure 2.42 SCI input/output timing in clock synchronous mode

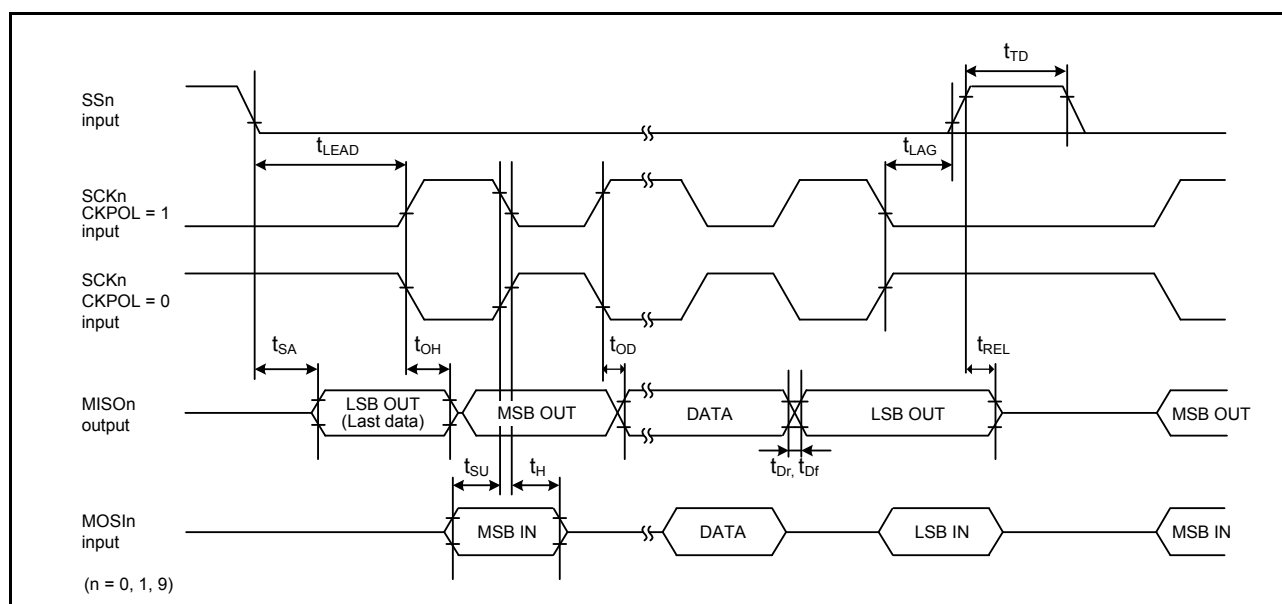


Figure 2.47 SCI simple SPI mode timing (slave, CKPH = 0)

Table 2.34 SCI timing (3)

Conditions: VCC = AVCC0 = 2.7 to 5.5 V

Parameter	Symbol	Min	Max	Unit	Test conditions
Simple IIC (Standard mode)	SDA input rise time	t_{Sr}	-	1000	ns
	SDA input fall time	t_{Sf}	-	300	ns
	SDA input spike pulse removal time	t_{SP}	0	$4 \times t_{IICcyc}$	ns
	Data input setup time	t_{SDAS}	250	-	ns
	Data input hold time	t_{SDAH}	0	-	ns
	SCL, SDA capacitive load	C_b^{*1}	-	400	pF
Simple IIC*2 (Fast mode)	SDA input rise time	t_{Sr}	-	300	ns
	SDA input fall time	t_{Sf}	-	300	ns
	SDA input spike pulse removal time	t_{SP}	0	$4 \times t_{IICcyc}$	ns
	Data input setup time	t_{SDAS}	100	-	ns
	Data input hold time	t_{SDAH}	0	-	ns
	SCL, SDA capacitive load	C_b^{*1}	-	400	pF

Note: t_{IICcyc} : Clock cycle selected by the SMR.CKS[1:0] bits.

Note 1. C_b indicates the total capacity of the bus line.

Note 2. Middle drive output is selected in the Port Drive Capability bit in the PmnPFS register.

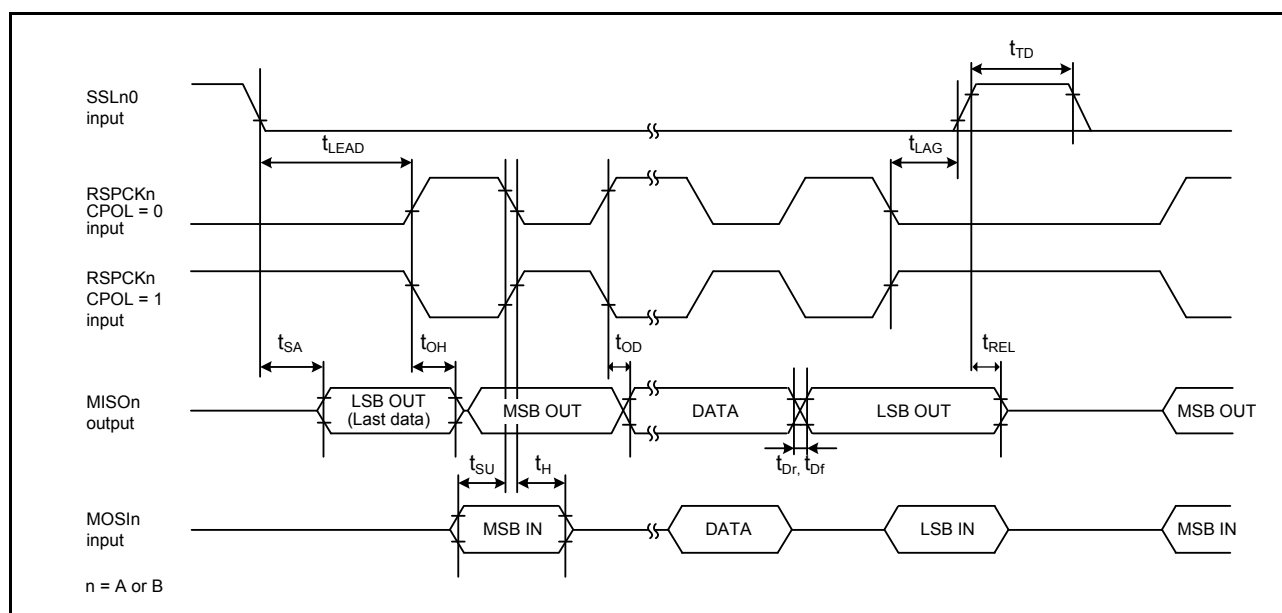


Figure 2.55 SPI timing (slave, CPHA = 1)

2.3.10 IIC Timing

Table 2.36 IIC timing

Conditions: VCC = AVCC0 = 2.7 to 5.5 V

Parameter		Symbol	Min*1	Max	Unit	Test conditions
IIC (standard mode, SMBus)	SCL input cycle time	t_{SCL}	$6 (12) \times t_{IICcyc} + 1300$	-	ns	Figure 2.56
	SCL input high pulse width	t_{SCLH}	$3 (6) \times t_{IICcyc} + 300$	-	ns	
	SCL input low pulse width	t_{SCLL}	$3 (6) \times t_{IICcyc} + 300$	-	ns	
	SCL, SDA input rise time	t_{Sr}	-	1000	ns	
	SCL, SDA input fall time	t_{Sf}	-	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	$1 (4) \times t_{IICcyc}$	ns	
	SDA input bus free time (When wakeup function is disabled)	t_{BUF}	$3 (6) \times t_{IICcyc} + 300$	-	ns	
	SDA input bus free time (When wakeup function is enabled)	t_{BUF}	$3 (6) \times t_{IICcyc} + 4 \times t_{Pcyc} + 300$	-	ns	
	START condition input hold time (When wakeup function is disabled)	t_{STAH}	$t_{IICcyc} + 300$	-	ns	
	START condition input hold time (When wakeup function is enabled)	t_{STAH}	$1 (5) \times t_{IICcyc} + t_{Pcyc} + 300$	-	ns	
	Repeated START condition input setup time	t_{STAS}	1000	-	ns	
	STOP condition input setup time	t_{STOS}	1000	-	ns	
	Data input setup time	t_{SDAS}	$t_{IICcyc} + 50$	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b	-	400	pF	
IIC*2 (Fast mode)	SCL input cycle time	t_{SCL}	$6 (12) \times t_{IICcyc} + 600$	-	ns	Figure 2.56
	SCL input high pulse width	t_{SCLH}	$3 (6) \times t_{IICcyc} + 300$	-	ns	
	SCL input low pulse width	t_{SCLL}	$3 (6) \times t_{IICcyc} + 300$	-	ns	
	SCL, SDA input rise time	t_{Sr}	-	300	ns	
	SCL, SDA input fall time	t_{Sf}	-	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	$1 (4) \times t_{IICcyc}$	ns	
	SDA input bus free time (When wakeup function is disabled)	t_{BUF}	$3 (6) \times t_{IICcyc} + 300$	-	ns	
	SDA input bus free time (When wakeup function is enabled)	t_{BUF}	$3 (6) \times t_{IICcyc} + 4 \times t_{Pcyc} + 300$	-	ns	
	START condition input hold time (When wakeup function is disabled)	t_{STAH}	$t_{IICcyc} + 300$	-	ns	
	START condition input hold time (When wakeup function is enabled)	t_{STAH}	$1(5) \times t_{IICcyc} + t_{Pcyc} + 300$	-	ns	
	Repeated START condition input setup time	t_{STAS}	300	-	ns	
	STOP condition input setup time	t_{STOS}	300	-	ns	
	Data input setup time	t_{SDAS}	$t_{IICcyc} + 50$	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b	-	400	pF	

Note: t_{IICcyc} : IIC internal reference clock (IICφ) cycle, t_{Pcyc} : PCLKB cycle

Note 1. Values in parentheses apply when ICMR3.NF[1:0] is set to 11b while the digital filter is enabled with ICFER.NFE set to 1.

Note 2. Middle drive output is selected in the Port Drive Capability bit in the PmnPFS register.

2.3.11 CLKOUT Timing

Table 2.37 CLKOUT timing

Parameter			Symbol	Min	Max	Unit*1	Test conditions
CLKOUT	CLKOUT pin output cycle*1	VCC = 2.7 V or above	t _{Cyc}	62.5	-	ns	Figure 2.57
		VCC = 1.8 V or above		125	-		
		VCC = 1.6 V or above		250	-		
	CLKOUT pin high pulse width*2	VCC = 2.7 V or above	t _{CH}	15	-	ns	
		VCC = 1.8 V or above		30	-		
		VCC = 1.6 V or above		150	-		
	CLKOUT pin low pulse width*2	VCC = 2.7 V or above	t _{CL}	15	-	ns	
		VCC = 1.8 V or above		30	-		
		VCC = 1.6 V or above		150	-		
	CLKOUT pin output rise time	VCC = 2.7 V or above	t _{Cr}	-	12	ns	
		VCC = 1.8 V or above		-	25		
		VCC = 1.6 V or above		-	50		
	CLKOUT pin output fall time	VCC = 2.7 V or above	t _{Cf}	-	12	ns	
		VCC = 1.8 V or above		-	25		
		VCC = 1.6 V or above		-	50		

Note 1. When the EXTAL external clock input or an oscillator is used with division by 1 (the CKOCR.CKOSSEL[2:0] bits are 011b and the CKOCR.CKODIV[2:0] bits are 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

Note 2. When the MOCO is selected as the clock output source (the CKOCR.CKOSSEL[2:0] bits are 001b), set the clock output division ratio selection to be divided by 2 (the CKOCR.CKODIV[2:0] bits are 001b).

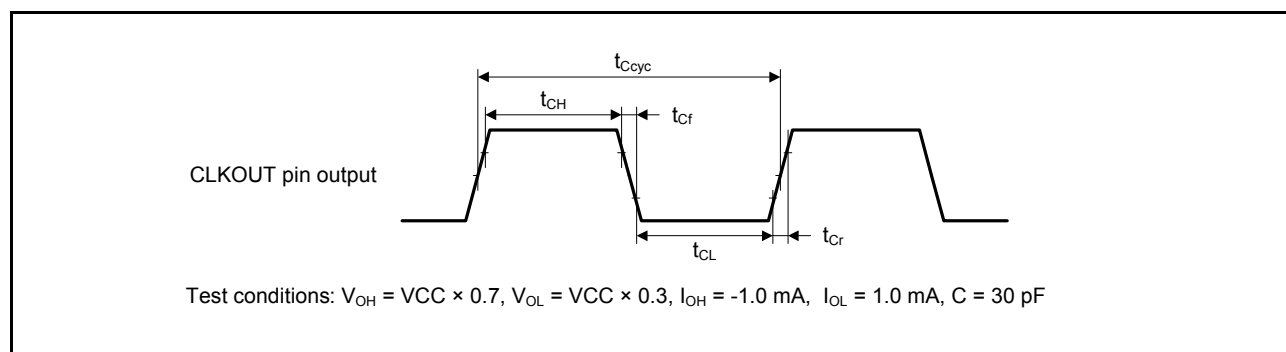


Figure 2.57 CLKOUT output timing

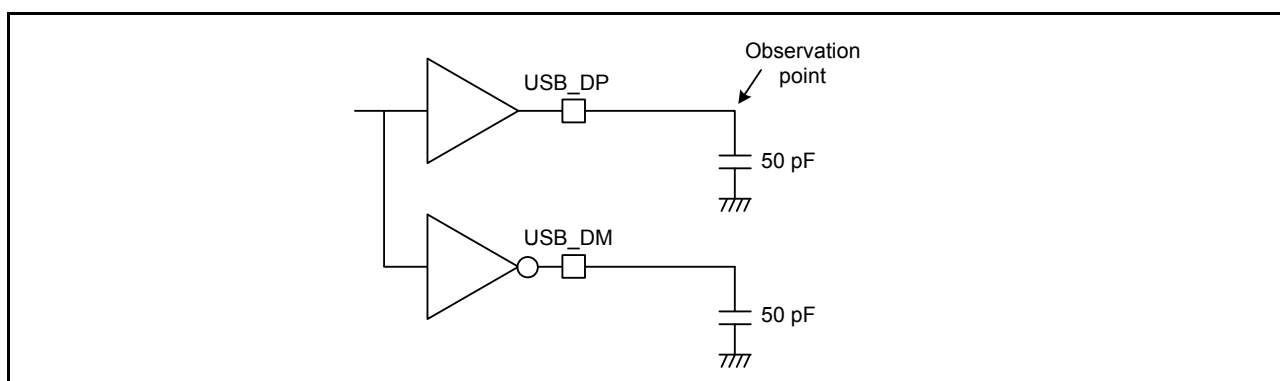


Figure 2.59 Test circuit for Full-Speed (FS) connection

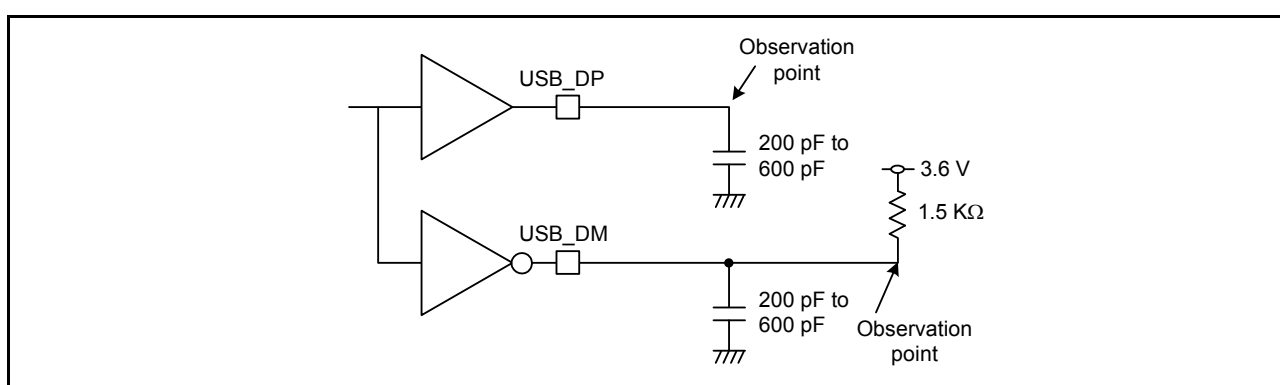


Figure 2.60 Test circuit for Low-Speed (LS) connection

2.4.2 USB External Supply

Table 2.39 USB regulator

Parameter		Min	Typ	Max	Unit	Test conditions
VCC_USB supply current	VCC_USB_LDO \geq 3.8V	-	-	50	mA	-
	VCC_USB_LDO \geq 4.5V	-	-	100	mA	-
VCC_USB supply voltage		3.0	-	3.6	V	-

2.5 ADC14 Characteristics

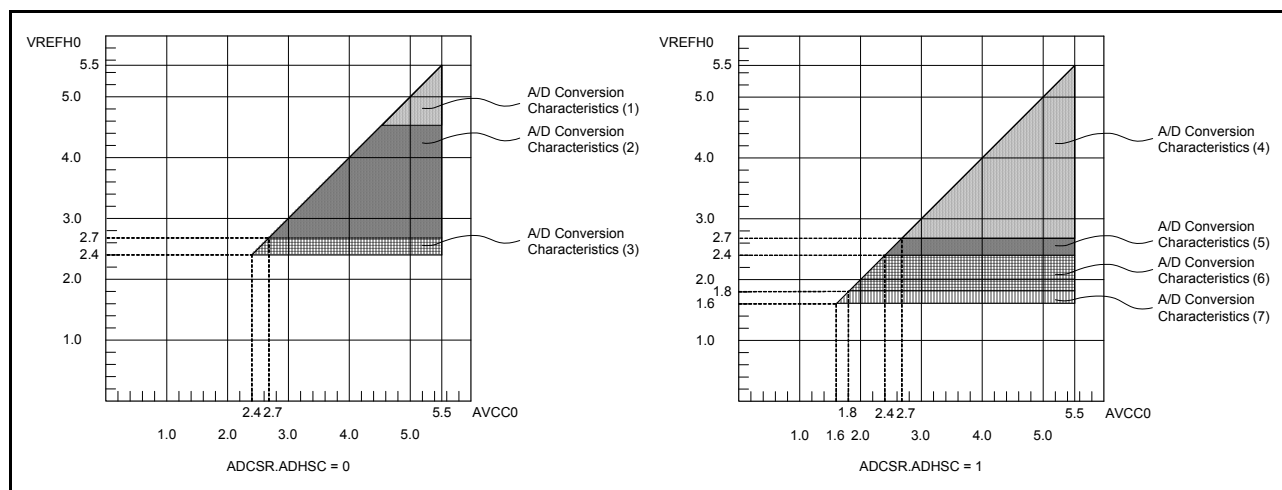


Figure 2.61 AVCC0 to VREFH0 voltage range

Table 2.40 A/D conversion characteristics (1) in high-speed A/D conversion mode (1 of 2)

Conditions: VCC = AVCC0 = 4.5 to 5.5 V, VREFH0 = 4.5 to 5.5 V, VSS = AVSS0 = VREFL0 = 0V

Reference voltage range applied to the VREFH0 and VREFL0.

Parameter		Min	Typ	Max	Unit	Test Conditions
Frequency		1	-	64	MHz	-
Analog input capacitance*2	Cs	-	-	8*3	pF	High-precision channel
		-	-	9*3	pF	Normal-precision channel
Analog input resistance	Rs	-	-	2.5*3	kΩ	High-precision channel
		-	-	6.7*3	kΩ	Normal-precision channel
Analog input voltage range	Ain	0	-	VREFH0	V	-
12-bit mode						
Resolution		-	-	12	Bit	-
Conversion time*1 (Operation at PCLKD = 64 MHz)	Permissible signal source impedance Max. = 0.3 kΩ	0.70	-	-	μs	High-precision channel ADCSR.ADHSC = 0 ADSSTRn.SST[7:0] = 0Dh
		1.13	-	-	μs	Normal-precision channel ADCSR.ADHSC = 0 ADSSTRn.SST[7:0] = 28h
Offset error		-	±0.5	±4.5	LSB	High-precision channel
				±6.0	LSB	Other than above
Full-scale error		-	±0.75	±4.5	LSB	High-precision channel
				±6.0	LSB	Other than above
Quantization error		-	±0.5	-	LSB	-
Absolute accuracy		-	±1.25	±5.0	LSB	High-precision channel
				±8.0	LSB	Other than above
DNL differential nonlinearity error		-	±1.0	-	LSB	-
INL integral nonlinearity error		-	±1.0	±3.0	LSB	-
14-bit mode						
Resolution		-	-	14	Bit	-

Table 2.45 A/D conversion characteristics (6) in low-power A/D conversion mode (2 of 2)

Conditions: VCC = AVCC0 = 1.8 to 5.5 V (AVCC0 = VCC when VCC < 2.0 V), VREFH0 = 1.8 to 5.5 V, VSS = AVSS0 = VREFL0 = 0 V
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter		Min	Typ	Max	Unit	Test Conditions
Conversion time*1 (Operation at PCLKD = 8 MHz)	Permissible signal source impedance Max. = 5 kΩ	6.75	-	-	μs	High-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 0Dh
		10.13	-	-	μs	Normal-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 28h
Offset error		-	±1.0	±7.5	LSB	High-precision channel
				±10.0	LSB	Other than above
Full-scale error		-	±1.5	±7.5	LSB	High-precision channel
				±10.0	LSB	Other than above
Quantization error		-	±0.5	-	LSB	-
Absolute accuracy		-	±3.0	±8.0	LSB	High-precision channel
				±12.0	LSB	Other than above
DNL differential nonlinearity error		-	±1.0	-	LSB	-
INL integral nonlinearity error		-	±1.0	±3.0	LSB	-
14-bit mode						
Resolution		-	-	14	Bit	-
Conversion time*1 (Operation at PCLKD = 8 MHz)	Permissible signal source impedance Max. = 5 kΩ	7.50	-	-	μs	High-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 0Dh
		10.88	-	-	μs	Normal-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 28h
Offset error		-	±4.0	±30.0	LSB	High-precision channel
				±40.0	LSB	Other than above
Full-scale error		-	±6.0	±30.0	LSB	High-precision channel
				±40.0	LSB	Other than above
Quantization error		-	±0.5	-	LSB	-
Absolute accuracy		-	±12.0	±32.0	LSB	High-precision channel
				±48.0	LSB	Other than above
DNL differential nonlinearity error		-	±4.0	-	LSB	-
INL integral nonlinearity error		-	±4.0	±12.0	LSB	-

Note: The characteristics apply when no pin functions other than 14-bit A/D converter input are used. Absolute accuracy does not include quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. The number of sampling states is indicated for the test conditions.

Note 2. Except for I/O input capacitance (Cin), see [section 2.2.4, I/O VOH, VOL, and Other Characteristics](#).

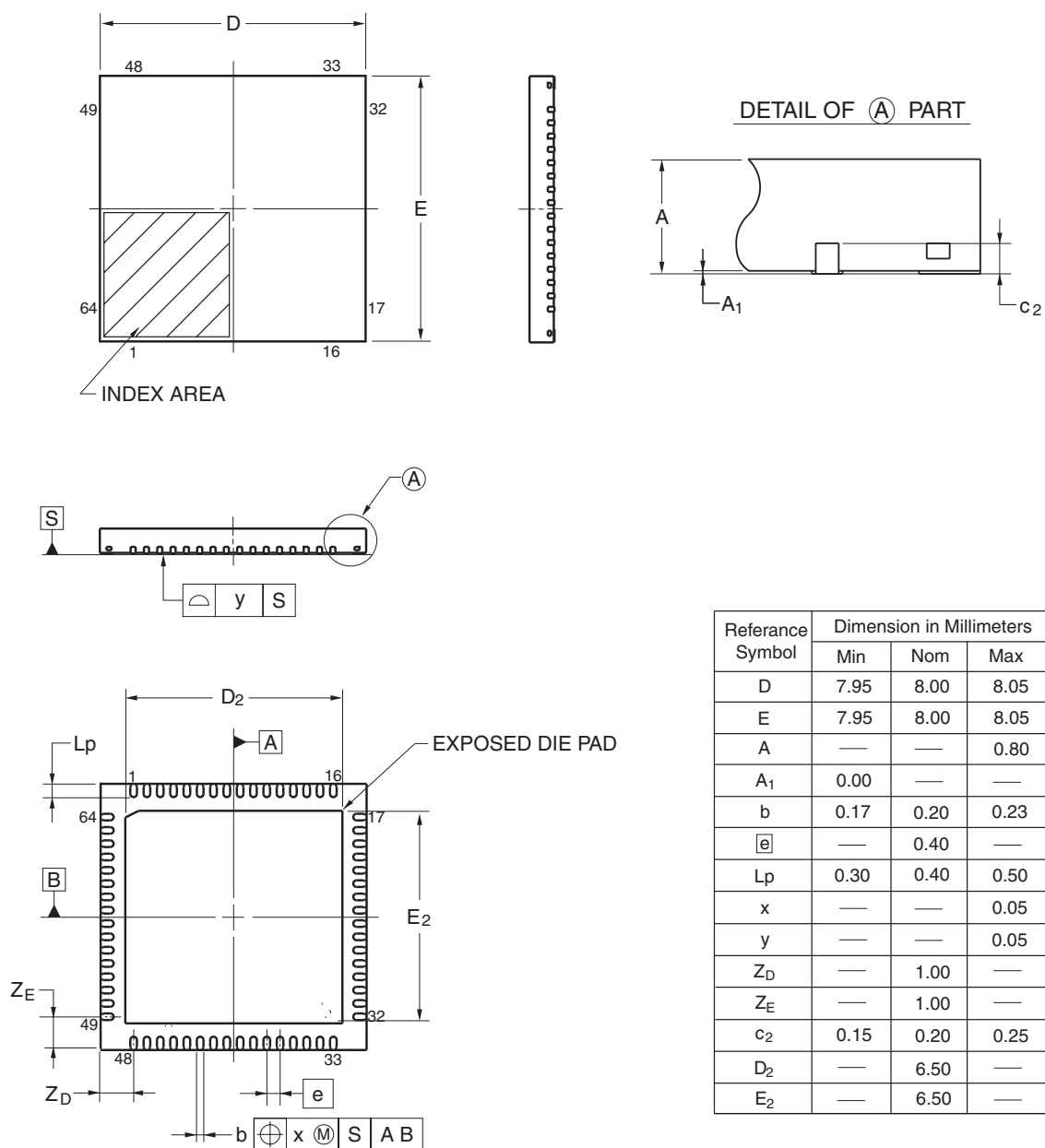
Note 3. Reference data.

Table 2.46 A/D conversion characteristics (7) in low-power A/D conversion mode (1 of 2)

Conditions: VCC = AVCC0 = 1.6 to 5.5 V (AVCC0 = VCC when VCC < 2.0 V), VREFH0 = 1.6 to 5.5 V, VSS = AVSS0 = VREFL0 = 0 V
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter		Min	Typ	Max	Unit	Test Conditions
Frequency		1	-	4	MHz	-
Analog input capacitance*2	Cs	-	-	8*3	pF	High-precision channel
		-	-	9*3	pF	Normal-precision channel
Analog input resistance	Rs	-	-	13.1*3	kΩ	High-precision channel
		-	-	14.3*3	kΩ	Normal-precision channel

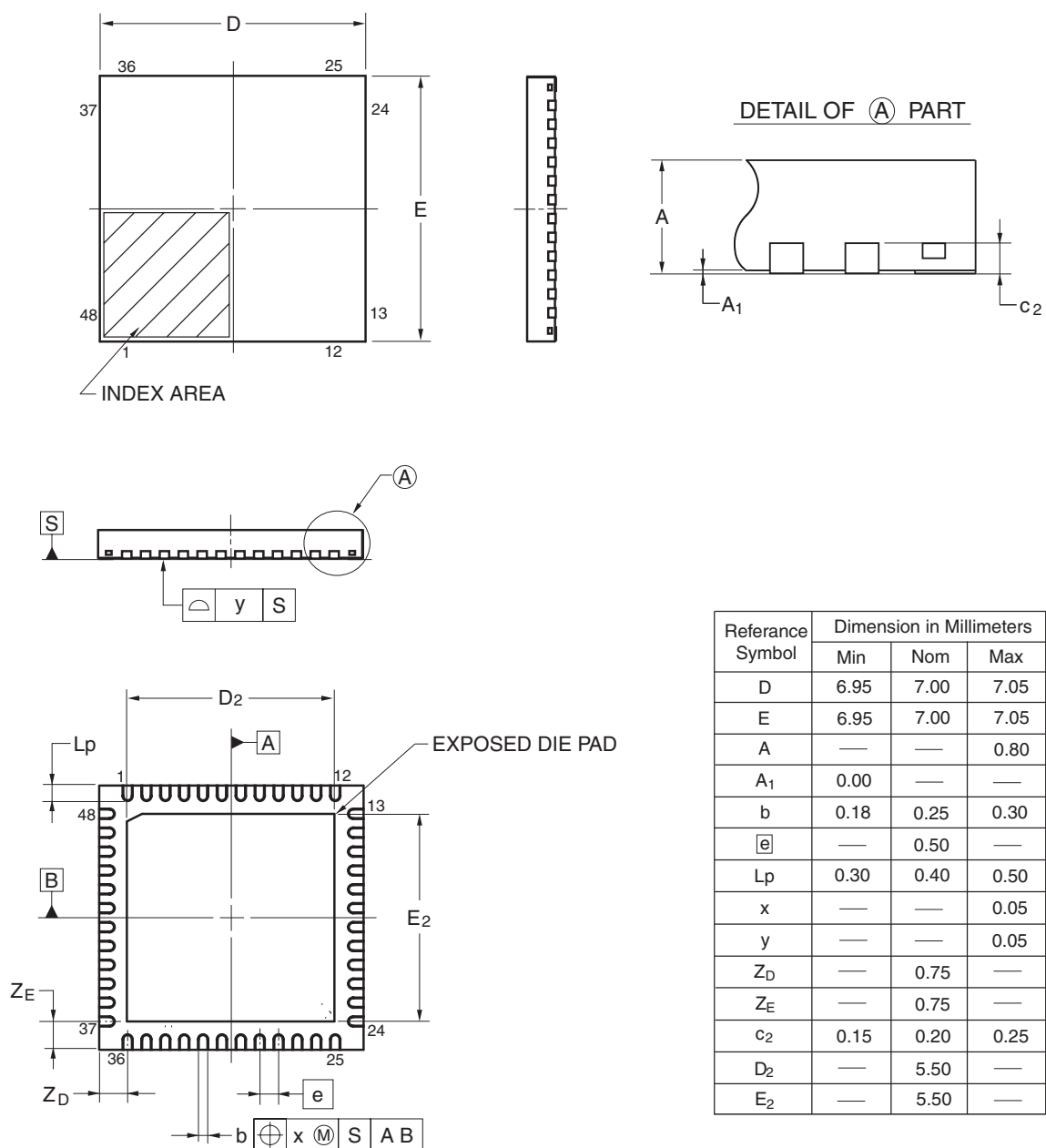
JEITA Package code	RENESAS code	Previous code	MASS(TYP.)[g]
P-HWQFN64-8x8-0.40	PWQN0064LA-A	P64K8-40-9B5-3	0.16



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Figure 1.4 QFN 64-pin

JEITA Package code	RENESAS code	Previous code	MASS(TYP.)[g]
P-HWQFN48-7x7-0.50	PWQN0048KB-A	48PJN-A P48K8-50-5B4-6	0.13



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Figure 1.5 QFN 48-pin

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